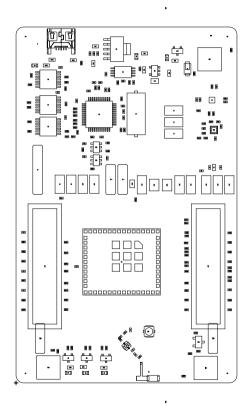
NOTES:

- 1. PCB VENDOR MUST BE UL QUALIFIED
- 2. BOARD MUST BE IDENTIFIED WITH APPROPRIATE VENDOR UL IDENTIFACTION MARK, DATE CODE
- 3. PCB MATERIAL UL FLAMMIBILITY RATING(94V-0 MINIMUM)
- 4. ALL DIMESION TOLERANCE AS BELOW UNLESS OTHERWISE SPECIFIED.
- 5. PCB LAYERS : 4 LAYERS
- 6. PCB THICKNESS : 1.2 mm+/-0.12 mm
- 7. TRACE WIDTHS TO BE FINISHED SIZES+/-1MIL
- 8. TOP SIDE SILKSCREEN : WHITE
 BOTTOM SIDE SILKSCREEN: WHITE
- 9. SOLDER MASK : <u>RED</u>, BOTH SIDES
- 10.MATERIAL : HF_FR4 TG: 150 CELSIUS
- 11.PLATING : OSP 0.2-0.6um[8-24uinch])

12.PCB Outline Dimension Tol: ROUTING :+/- 0.13mm

> 0.8mil(min) $(0.4 \sqrt{1.2} \text{mil})$ 1.7 +/-0.4 mil(H/1oz Finished) Λ ∕Copper Top(L Perpeg 4.8 +/-0.5 mil Copper Mid1(L2) 1.2 +/-0.2 mil(1oz) 1.2 + / - 0.12 mmCore 31.0+/-2.9 mil (47.40 + / - 4.72 mil)..2 + /-0.2 mil(1oz)Perpeg 4.8 +/-0.5 mil Copper Bot(L4) 1.7 +/-0.4 mil(H/1oz Finished) $\sqrt{}$ (0.4\1.2mil)

ART FILM - PCB_NOTE



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